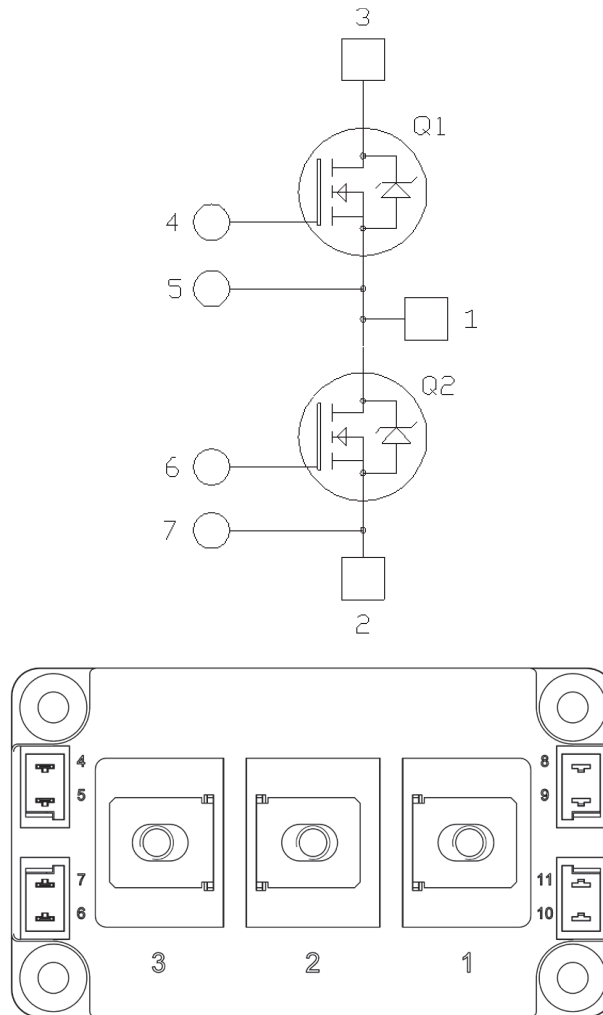


## Phase Leg SiC Power Module

### Product Overview

The MSCSM120AM027D3AG device is a full bridge 1200V, 733A phase leg silicon carbide (SiC) MOSFET power module.



**Note:** All ratings at  $T_J = 25^\circ\text{C}$ , unless otherwise specified.



These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

## Features

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The following are the key features of the MSCSM120AM027D3AG device:

- SiC Power MOSFET
  - Low  $R_{DS(on)}$
  - High temperature performance
- Kelvin source for easy drive
- High level of integration
- M6 power connectors
- Aluminum Nitride (AlN) substrate for improved thermal performance

## Benefits

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The following are the benefits of MSCSM120AM027D3AG device:

- High efficiency converter
- Stable temperature behavior
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant

## Application

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The MSCSM120AM027D3AG device is designed for the following applications:

- Welding converters
- Switched mode power supplies
- Uninterruptible power supplies
- EV motor and traction drive

## 1. Electrical Specifications

This section provides the electrical specifications of the MSCSM120AM027D3AG device.

### 1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings per SiC MOSFET of the MSCSM120AM027D3AG device.

**Table 1-1. Absolute Maximum Ratings**

Symbol	Parameter		Maximum Ratings	Unit
$V_{DS}$	Drain-Source voltage		1200	V
$I_D$	Continuous drain current	$T_C = 25\text{ }^{\circ}\text{C}$	733 <sup>1</sup>	A
		$T_C = 80\text{ }^{\circ}\text{C}$	584 <sup>1</sup>	
$I_{DM}$	Pulsed drain current		1400	
$V_{GS}$	Gate-Source voltage		–10/23	V
$R_{DS(on)}$	Drain-Source ON resistance		3.5	mΩ
$P_D$	Power dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	2970	W

**Note:**

1. SiC MOSFET device specification, but the output current must be limited due to the size of the power connectors.

The following table lists the electrical characteristics per SiC MOSFET of the MSCSM120AM027D3AG device.

**Table 1-2. Electrical Characteristics**

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0V$ $V_{DS} = 1200V$		—	90	900	μA
$R_{DS(on)}$	Drain–Source on resistance	$V_{GS} = 20V$ $I_D = 360A$	$T_J = 25\text{ }^{\circ}\text{C}$	—	2.8	3.5	mΩ
			$T_J = 175\text{ }^{\circ}\text{C}$	—	4.5	—	
$V_{GS(th)}$	Gate threshold voltage	$V_{GS} = V_{DS}$ $I_D = 27\text{ mA}$		1.8	2.8	—	V
$I_{GSS}$	Gate–Source leakage current	$V_{GS} = 20V$ ; $V_{DS} = 0V$		—	—	900	nA

The following table lists the dynamic characteristics per SiC MOSFET of the MSCSM120AM027D3AG device.

**Table 1-3. Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{GS} = 0V$	—	27	—	nF
$C_{oss}$	Output capacitance	$V_{DS} = 1000V$	—	2.43	—	
$C_{rss}$	Reverse transfer capacitance	$f = 1\text{ MHz}$	—	0.23	—	
$Q_g$	Total gate charge	$V_{GS} = -5V/20V$	—	2088	—	nC
$Q_{gs}$	Gate-Source charge	$V_{Bus} = 800V$	—	369	—	
$Q_{gd}$	Gate-Drain charge	$I_D = 360A$	—	450	—	
$T_{d(on)}$	Turn-on delay time	$V_{GS} = -5V/20V$	$T_J = 150^\circ C$	74	—	ns
$T_r$	Rise time	$V_{Bus} = 600V$		96	—	
$T_{d(off)}$	Turn-off delay time	$I_D = 450A$		150	—	
$T_f$	Fall time	$R_{G(on)} = 4.7\Omega$ $R_{G(off)} = 1.8\Omega$		51	—	
$E_{on}$	Turn-on energy	$V_{GS} = -5V/20V$	$T_J = 150^\circ C$	16	—	mJ
$E_{off}$	Turn-off energy	$V_{Bus} = 600V$ $I_D = 450A$ $R_{G(on)} = 4.7\Omega$ $R_{G(off)} = 1.8\Omega$		9.2	—	
$R_{Gint}$	Internal gate resistance		—	0.65	—	$\Omega$
$R_{thJC}$	Junction-to-case thermal resistance		—	—	0.051	$^\circ C/W$

The following table lists the body diode ratings and characteristics per SiC MOSFET of the MSCSM120AM027D3AG device.

**Table 1-4. Body Diode Ratings and Characteristics**

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$V_{SD}$	Diode forward voltage	$V_{GS} = 0V$ ; $I_{SD} = 360A$	—	4	—	V
		$V_{GS} = -5V$ ; $I_{SD} = 360A$	—	4.2	—	
$t_{rr}$	Reverse recovery time	$I_{SD} = 360A$ ; $V_{GS} = -5V$	—	90	—	ns
$Q_{rr}$	Reverse recovery charge	$V_R = 600V$ ; $di_F/dt = 9000\text{ A}/\mu s$	—	4950	—	nC
$I_{rr}$	Reverse recovery current		—	122	—	A

### 1.2 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM120AM027D3AG device.

**Table 1-5. Thermal and Package Characteristics**

Symbol	Characteristics			Min.	Max.	Unit
V <sub>ISOL</sub>	RMS isolation voltage, any terminal to case t =1 min, 50 Hz/60 Hz			4000	—	V
T <sub>J</sub>	Operating junction temperature range			−40	175	°C
T <sub>JOP</sub>	Recommended junction temperature under switching conditions			−40	T <sub>Jmax</sub> −25	
T <sub>STG</sub>	Storage temperature range			−40	125	
T <sub>C</sub>	Operating case temperature			−40	125	
Torque	Mounting torque	For terminals	M6	3	5	N.m
		To heatsink	M6	3	5	
Wt	Package weight			—	350	g

### 1.3 Typical SiC MOSFET Performance Curve

This section shows the typical SiC MOSFET performance curves of the MSCSM120AM027D3AG device.

Figure 1-1. Maximum Thermal Impedance

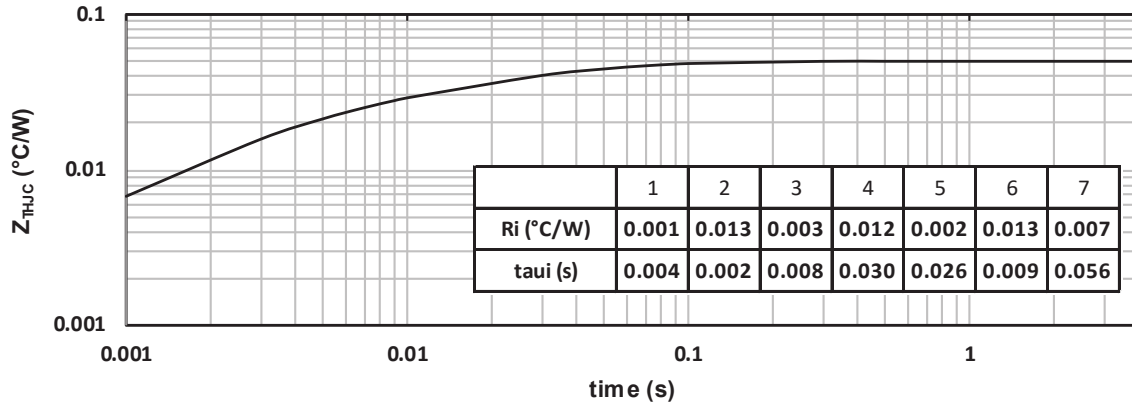


Figure 1-2. Output Characteristics,  $T_J = 25^\circ\text{C}$

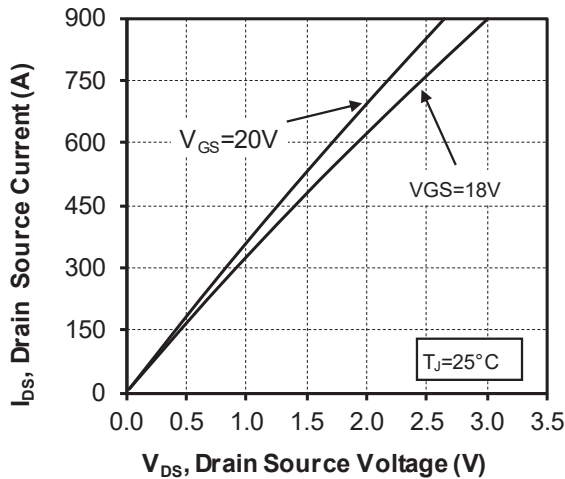


Figure 1-3. Output Characteristics,  $T_J = 175^\circ\text{C}$

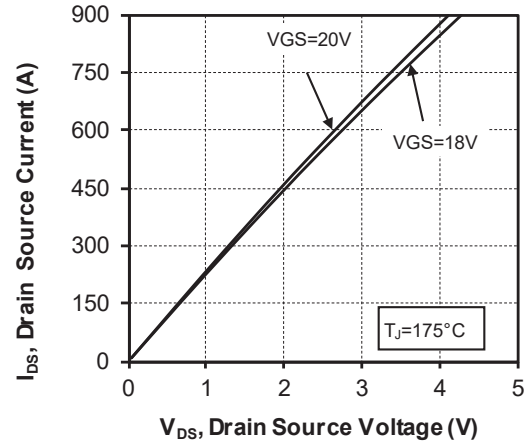


Figure 1-4. Normalized  $R_{DS(on)}$  vs. Temperature

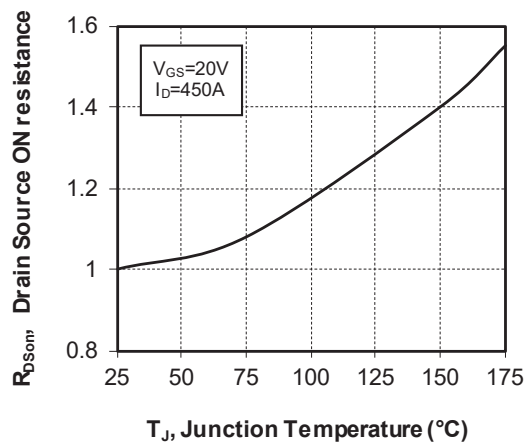


Figure 1-5. Transfer Characteristics

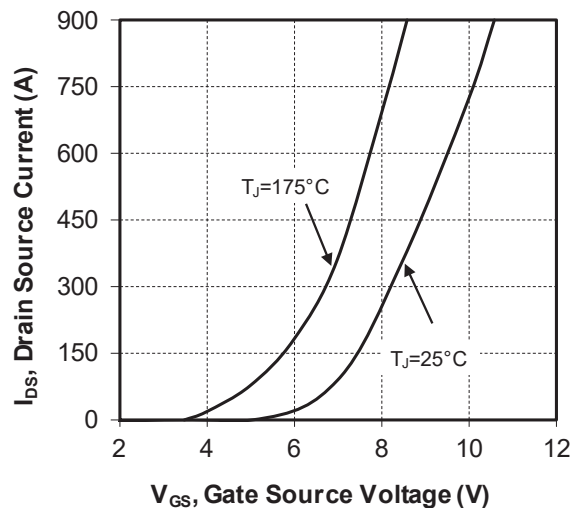


Figure 1-6. Switching Energy vs. Current

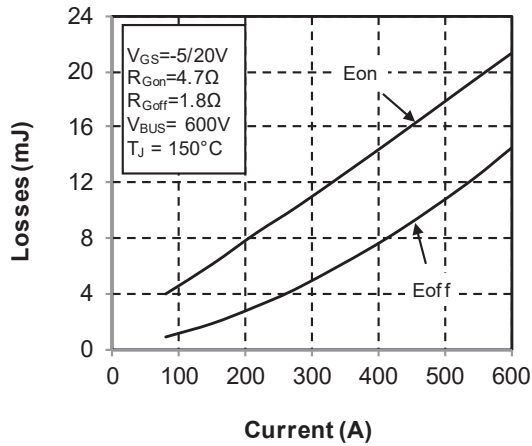


Figure 1-7. Switching Energy vs.  $R_g$

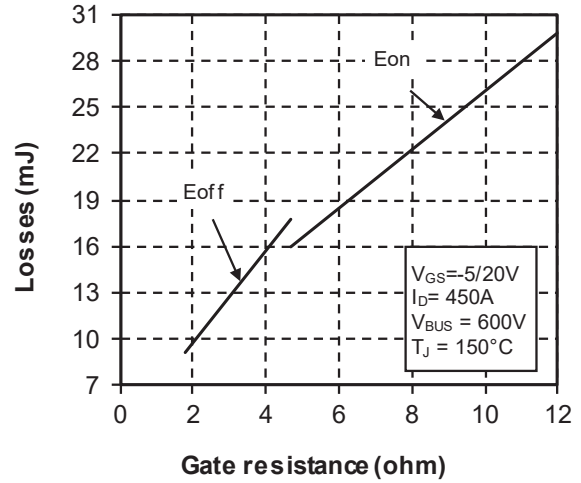


Figure 1-8. Capacitance vs. Drain Source Voltage

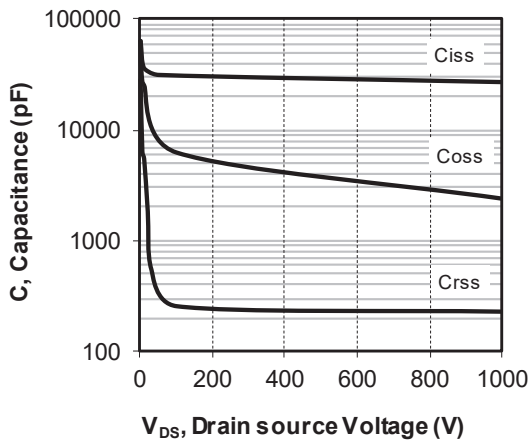


Figure 1-9. Gate Charge vs. Gate Source Voltage

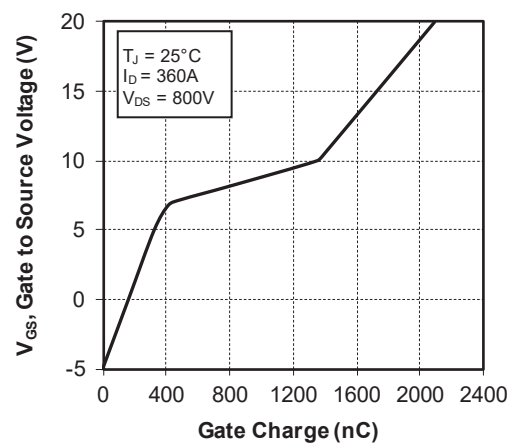


Figure 1-10. Body Diode Characteristics,  $T_J = 25^\circ C$

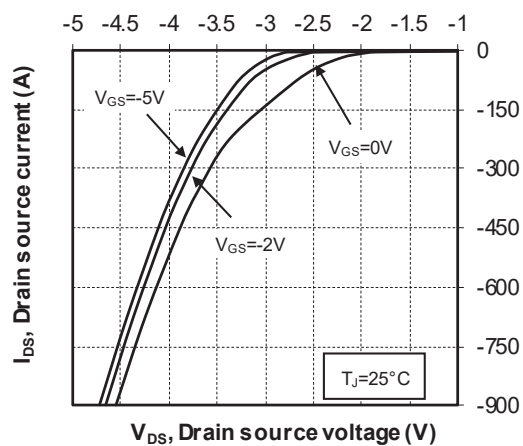


Figure 1-11. 3<sup>rd</sup> Quadrant Characteristics,  $T_J = 25^\circ C$

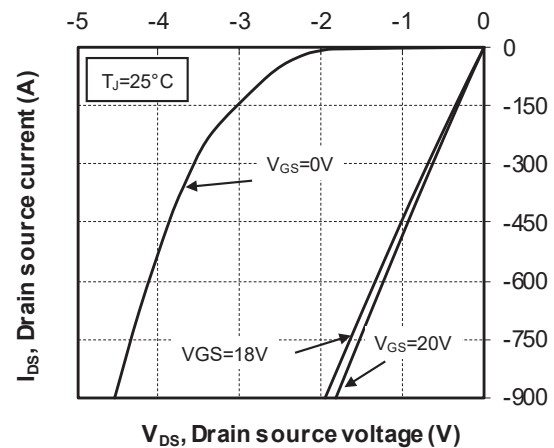


Figure 1-12. Body Diode Characteristics,  $T_J = 175^\circ\text{C}$  Figure 1-13. 3<sup>rd</sup> Quadrant Characteristics,  $T_J = 175^\circ\text{C}$

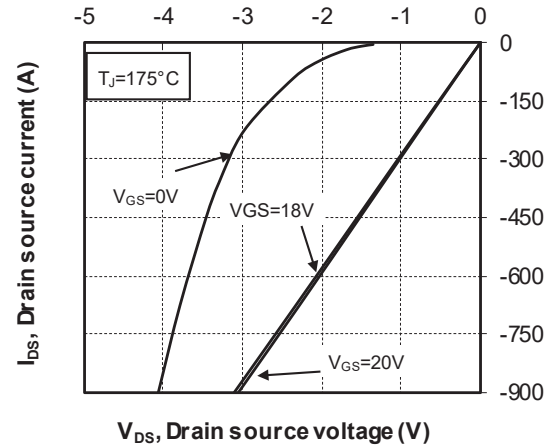
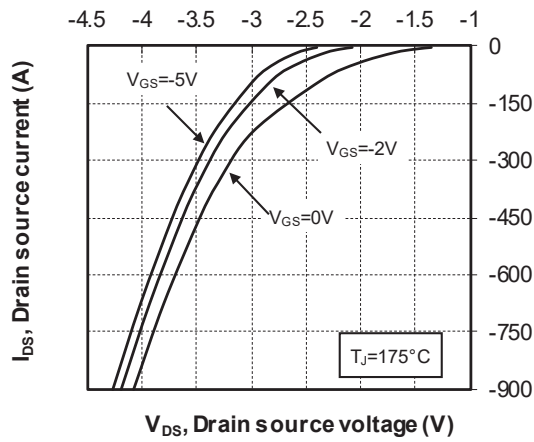
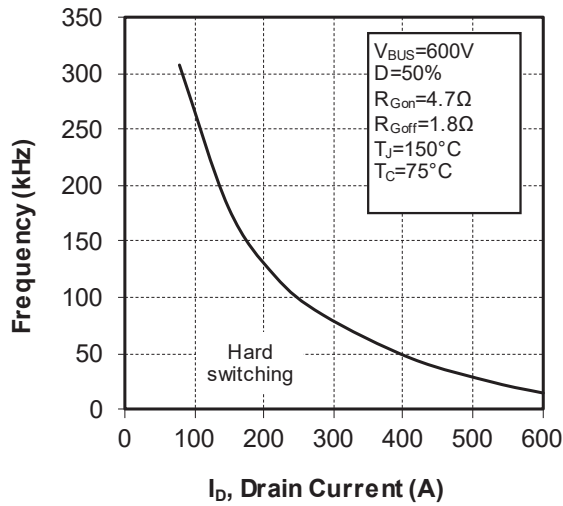


Figure 1-14. Operating Frequency vs Drain Current





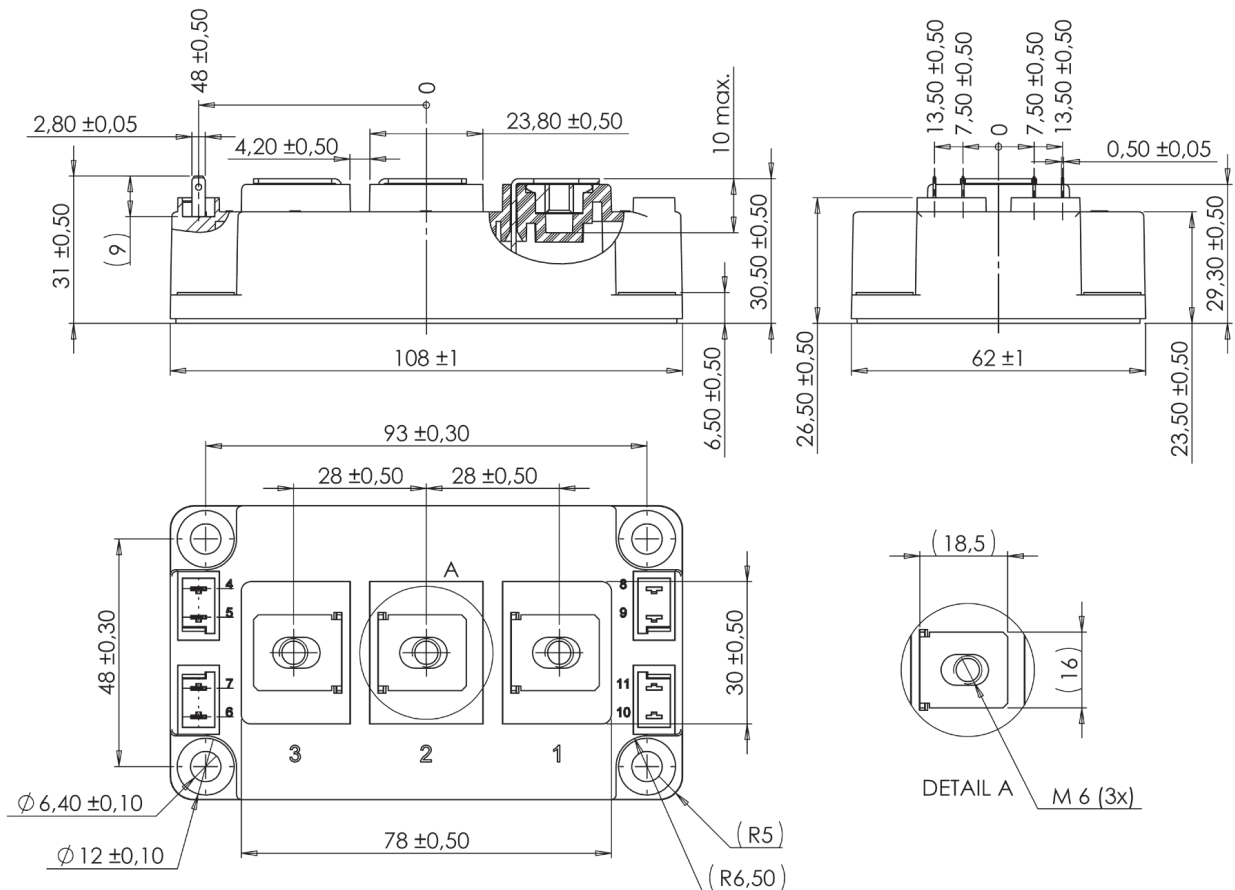
## 2. Package Specifications

The following section shows the package specification of the MSCSM120AM027D3AG device.

### 2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM120AM027D3AG device. The dimensions in the following figure are in millimeters.

**Figure 2-1. Package Outline Drawing**



**Note:** See [AP1908—Mounting instruction for D3 and D4 Power Modules](#) for more information.

### 3. Revision History

Revision	Date	Description
A	06/2022	Initial Revision.

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